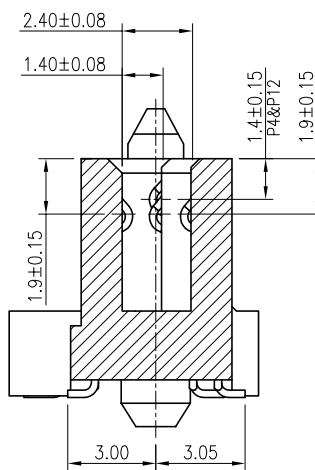
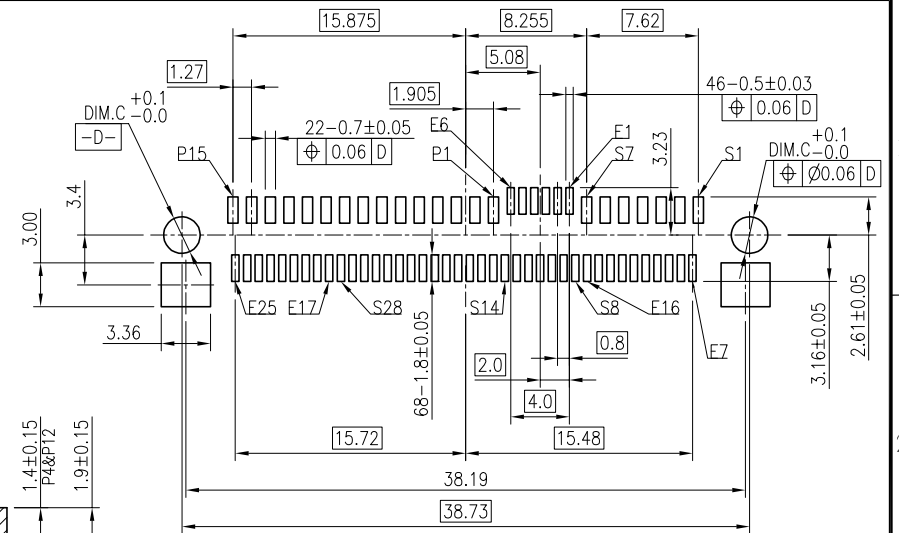


WITH PICK-UP CAP
SCALE 1:1



SECTION C-C
SCALE 4:1



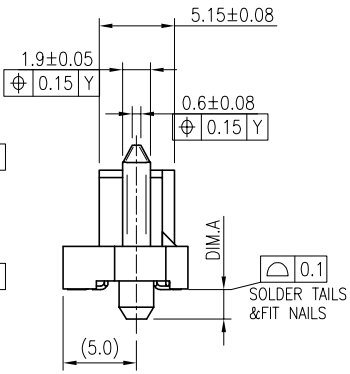
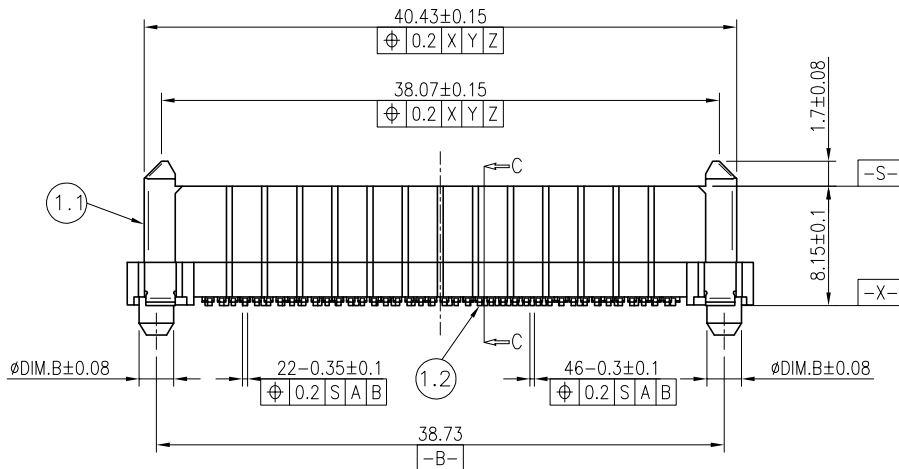
RECOMMENDED P.C.B. LAYOUT

- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0; COLOR:BLACK.
 - CONTACT: COPPER ALLOY
 - FIT NAIL: COPPER ALLOY
 - PICK-UP CAP: THERMOPLASTIC, HIGH TEMP.,UL94V-0; COLOR:BLACK.
 - FINISH:
 - CONTACT:
 - GOLD PLATING ON CONTACT AREA.
 - 100~200u" MATTE TIN PLATING ON SOLDER TAILS.
 - 50~100u" NICKEL UNDERPLATING OVERALL.
 - FIT NAIL:
 - 100~200u" MATTE TIN PLATING ON SOLDER TAILS.
 - 50~100u" NICKEL UNDERPLATING OVERALL.
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-52962-XXXX-XXX
 - PACKAGE PLS. REFER TO 52960-XXXX-XX-TRP
 - PART NUMBER

52960-068 X X-XXX

NO OF CKT X TYPE
XXX.CKT 001:BOSS TYPE
 003:BOSS TYPE

PACKING PLATING
7:TAPE&REEL WITH CAP D: 30u" GOLD PLATING



PART NO.	DIM. A	DIM. B	DIM. C
52960-068xx-001	2.00	2.36	2.50
52960-068xx-003	1.00	0.80	0.90

QUALITY SYMBOLS MAJOR CRITICAL GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Lee, I Hung CHECKED BY Chen, Chun Yuan APPROVED BY Wang, Chun Sheng	DATE 18/12/12 DATE 18/12/12 DATE 18/12/12			
	TITLE 1.27/0.8 PITCH SAS+PCIE 12G RECEPTACLE VERTICAL SMT TYPE			DWG NO. 52960-068XX-XXX	
UNITS mm		SCALE 2:1	SHEET NO. 1 OF 1	REV A	PART NO. SEE NOTES